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[REDACTED]

Attachment:

Section 3: PRIOR ART

Description or
Comments:

[REDACTED]

Attachment:

Section 4: NEW TECHNOLOGY

Description or
Comments:

This mechanism has been developed to separate the individual boards out of the mother board without causing damage to components. The mechanism supports the boards while supplying a force which breaks the boards in the fault line created by the scoring process. Complete separation is accomplished in several steps. This mechanism is combined with a feed system and programmable logic controller to provide a complete machine. This machine has the capability to be used totally in line by using conveyors to transport

the mother boards in and transport separated modules out. Currently the machine is set up to use an operator which will place a mother board into the machine, press the start buttons, remove finished boards from a tray which is mounted on the exit side of machine.

Attachment:

See Section:9 ATTACHMENTS

Section 5: DETAILED DESCRIPTION

**Description or
Comments:**

Attachment:

See Section:9 ATTACHMENTS

Section 6: DATES

Record(s) of Completion:

Date of Completion:

First Production Use:

[Model and Date]

Section 7: CATEGORY QUESTIONS

Invention Category:

Section 8: MISCELLANEOUS ITEMS

Is it a Government Contract?:

If yes, Government Contract Number:

**Identify a government agreement,
partnership, consortium, or other
company involved with conception or
first building of the invention:**

**If disclosed to non-Company
personnel, identify recipient and date:**

Section 9: ATTACHMENTS

File Name	Description
[REDACTED]	[REDACTED]
[REDACTED]	[REDACTED]

Section 10: INVENTORSHIP

CDS or Other Id:

Last Name:

First Name:

Middle Name:

Employment Category:

Employment Status:

Job Title:

Email:

Office Phone Number:

Fax:

Social Security or Company ID Number: [This field is blocked out intentionally.]

Citizenship:

Home Address Line 1:

Home Address Line 2:

City, State & Zip Code:

Country Code:

Employee of:

Department:

Organization Code:

Payroll Location Code:

Office Address:

Maildrop:

Supervisor's CDS Id:

Manager's CDS Id:

CDS or Other Id:

Last Name:

First Name:

Middle Name:

Employment Category:

Employment Status:

Job Title:

Email:

Office Phone Number:

Fax:

**Social Security or Company ID
Number:**

Citizenship:

Home Address Line 1:

Home Address Line 2:

City, State & Zip Code:

Country Code:

Employee of:

Department:

Organization Code:

Payroll Location Code:

Office Address:

Maildrop:

Supervisor's CDS Id:

Manager's CDS Id:

Online Invention Disclosure

Web Hub

Related Links: [View Invention Disclosure](#) | [Assign/Evaluate Disclosure](#) | [View Invention Ranking](#)

Online Invention Disclosure: View Invention Disclosure

Inv. Discl. Docket No: [REDACTED]
Creation Date: [REDACTED]
Author: [REDACTED]
Approval to submit was given by: [REDACTED]

Section 1: INVENTION DESCRIPTION

Title of Invention: A MACHINE FOR SEPARATING INDIVIDUAL
CIRCUIT BOARDS FROM A MULTIPLE
PRE-SCORED BOARD ARRAY.

Patent Evaluation Committee: VI
CPSC Code: &
Originating Country Code: US
Internal Reference Number: [REDACTED]

Section 2: PROBLEM & SOLUTION

Description or Comments: [REDACTED]